

# IEEE 802.3cg 10SPE TF AdHoc meeting

## 6 February 2019

Prepared by George Zimmerman

### Proposed Agenda:

1. Agenda/Admin George Zimmerman
2. Coupling Attenuation SPE-I link segment Update Dieter Schicketanz
3. IEEE P802.3cg 10BASE-T1S Relationship of PLCA to the Layered Stack Model David Brandt

### Presentations posted at:

<http://www.ieee802.org/3/cg/public/adhoc/index.html>

### Agenda/Admin George Zimmerman:

Meeting began at 7:05am PT.

1. Reviewed the Attendance information related to the ad hoc(s).
2. Displayed post-par slide deck, reviewed patent policy, participation conditions.  
<https://development.standards.ieee.org/myproject/Public/mytools/mob/slideset.ppt> (10SPE)  
<https://mentor.ieee.org/802-ec/dcn/17/ec-17-0093-05-OPNP-ieee-802-participation-slide-ppt.ppt>
3. Made potentially essential patents call for 802.3cg – 10SPE at 7:09am PT.  
No-one responded.
4. Reminded participants to indicate full names and employer/affiliation correctly for the meeting minutes.

### Discussion of presentations

#### Coupling Attenuation SPE-I link segment update

**Dieter Schicketanz Reutlingen University**

- Discussion of what cables may do, rather than what they need to do for 10BASE-T1L
- Test method IEC NP reference in clause 146 is moving to a different IEC specification – may need to be replaced with new reference put to the bibliography.

#### 3. IEEE P802.3cg 10BASE-T1S Relationship of PLCA to the Layered Stack Model David Brandt, Rockwell Automation

- Reviewed relationship of PLCA to the OSI layered stack model, discussing physical layer vs. data link layer / MAC functionality in that model and in 802.3 clause 4.

Meeting closed – 7:57am PT

## Attendees (from Webex + emails)

Name	Employer	Affiliation	Attended 02/06
Aniruddha Phatak	Renesas	Renesas	y
Brett McClellan	Marvell	Marvell	y
Brian Franchuk	Emerson	Emerson	y
Chris Pohl	Beckhoff Automation	Beckhoff Automation	y
Clark Carty	Cisco	Cisco	y
Cyrus Kelly	Relcom Inc.	Relcom Inc.	y
Dave Hess	CordData	CordData	y
David Brandt	Rockwell Automation	Rockwell Automation	y
Dieter Schicketanz	Consultant, Reutlingen University	Consultant, Reutlingen University	y
Doug Oliver	Ford	Ford	y
Fatma Caliskan	MicroChip	Microchip	y
Geoff Thompson	GraCaSI S.A.	Independent	y
George Zimmerman	CME Consulting	ADI, APL Group, Aquantia, BMW, Cisco, Commscope	y
Gergely Huszak	Kone	Kone	y
Haysam Kadry	Ford	Ford	y
Hongming An	Microchip	Microchip	y
James Withey	Fluke	Fluke	y
Jes Asmussen	Rockwell Automation	Rockwell Automation	y
Jim Lawlis	Ford	Ford	y
Lars Mickan	Renesas	Renesas	y
Laura Schweitz	Turck	Turck	y
Maris Graube	Relcom Inc.	Relcom Inc.	y
Martin Miller	Microchip	Microchip	y
Masood Shariff	CommScope	CommScope	y
Matthias Fritsche	HARTING Electronics GmbH	HARTING Electronics GmbH	y
Michal Brychta	Analog Devices	Analog Devices	y
Mick McCarthy	Analog Devices	Analog Devices	y
Natalie Wienckowski	GM	GM	y
Niall Fitzgerald	acuitas silicon	acuitas silicon	y
Oisín Ó Cuanacháin	Analog Devices	Analog Devices	y
Olindo Savi	Hubbell	Hubbell	y
Paul Neveux	Superior Essex	Superior Essex	y
Phillip Brownlee	TDK	TDK	y
Piergiorgio Beruto	Canova Tech	Canova Tech	y
Ron Tellas	Belden	Belden	y
Scott Griffiths	Rockwell Automation	Rockwell Automation	y

Steffen Graber	Pepperl+Fuchs	Pepperl+Fuchs	y
Tim Baggett	Microchip	Microchip	y
Todd Harpel	Nexans	Nexans	y
Ulrich Egenhofer	Draexlmaier	Draexlmaier	y
Venkataraman Iyer	Microchip	Microchip	y
Vimalli Raman	Yazaki	Yazaki	y
Woojung Huh	Microchip	Microchip	y
Attendees			43